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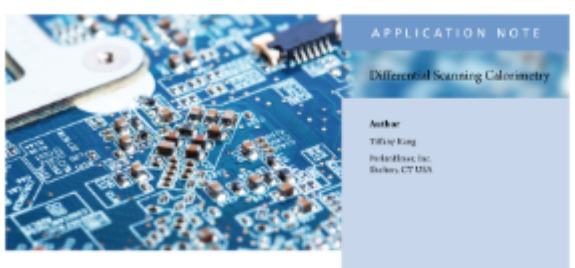

Curing of an Optical Adhesive by UV Irradiation by DSC

Optical adhesives are used in many industries such as semiconductors and chip manufacturing where solvents are undesirable. Power compensated instruments are the best choice for fast analysis of the curing profile and measurement of the energy of curing reactions as the design allows quick detection and response to changes in the optical material. This application note describes how Photo-DSC using power compensation technique is a powerful tool for studying and quantitatively characterizing optically curing materials.

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